

**AMENDMENT TO THE SPECIFICATION**

Paragraph bridging pages 2 and 3, please amend as follows:

According to this method, the wafer after the backside grinding is reinforced by the resin film, and the individual chips cut away from the wafer are reinforced by the resin film as well. It is thus possible to handle the wafer and the chips in a satisfactory manner without causing any breaking. In addition, because mounting of the chips can be achieved by connecting the exposed top portion of the protruding electrodes to electrode pads on a wiring board, the semiconductor device can be reduced in thickness markedly in comparison with an arrangement such that an external terminals are drawn through wire bonding.

Paragraph bridging pages 5 and 6, please amend as follows:

Further, because copper is an element that readily migrates, for example, in a case where the resin film is made of polyimide that readily absorbs moisture, if neighboring posts are formed too close, these posts ~~electrical~~ electrically short-circuit due to migration. Hence, a wide space needs to be secured between neighboring posts, which is a factor that makes miniaturization of the semiconductor device difficult.